



Material Content Data Sheet



Sales Product Name	TLE4208G			Issued	16. June 2015			
MA#	MA001102832							
Package	PG-DSO-28-41			Weight*	834.61 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	11.786	1.41	1.41	14122	14122
leadframe	inorganic material	phosphorus	7723-14-0	0.073	0.01		87	
	non noble metal	zinc	7440-66-6	0.292	0.04		350	
	non noble metal	iron	7439-89-6	5.837	0.70		6994	
wire	non noble metal	copper	7440-50-8	237.007	28.40	29.15	283974	291405
	non noble metal	copper	7440-50-8	0.406	0.05	0.05	487	487
	encapsulation	organic material	carbon black	1333-86-4	1.136	0.14		1361
encapsulation	plastics	epoxy resin	-	52.241	6.26		62593	
	inorganic material	silicondioxide	60676-86-0	514.459	61.62	68.02	616407	680361
leadfinish	non noble metal	tin	7440-31-5	4.913	0.59	0.59	5887	5887
plating	noble metal	silver	7440-22-4	1.897	0.23	0.23	2273	2273
glue	plastics	epoxy resin	-	1.140	0.14		1366	
	noble metal	silver	7440-22-4	3.421	0.41	0.55	4099	5465
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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